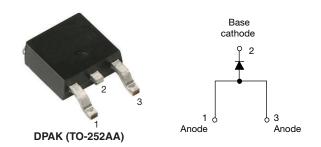


COMPLIANT HALOGEN

**FREE** 

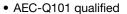
# High Voltage Surface Mount Input Rectifier Diode, 8 A



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	8 A			
$V_{R}$	1600 V			
V <sub>F</sub> at I <sub>F</sub>	1.1 V			
I <sub>FSM</sub>	150 A			
T <sub>J</sub> max.	150 °C			
Package	DPAK (TO-252AA)			
Circuit configuration	Single			

#### **FEATURES**

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



- Meets JESD 201 class 2 whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V<sub>F</sub> rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- On-board and off-board EV / HEV battery chargers
- Renewable energy inverters

### **DESCRIPTION**

The VS-8EWS16SLHM3 rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage.

The **high reverse voltage** range available allows design of input stage primary rectification with **outstanding voltage surge** capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS							
APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS				
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 µm) copper	1.2	1.6	٨				
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	Α				
Aluminum IMS with heatsink, R <sub>thCA</sub> = 5 °C/W	5.5	6.5					

#### Note

•  $T_A = 55$  °C,  $T_J = 125$  °C, footprint 300 mm<sup>2</sup>

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL	CHARACTERISTICS	VALUES	UNITS					
I <sub>F(AV)</sub>	Sinusoidal waveform	8	A					
V <sub>RRM</sub>		1600	V					
I <sub>FSM</sub>		150	A					
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V					
T <sub>J</sub>		-40 to +150	°C					

VOLTAGE RATINGS							
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA				
VS-8EWS16SLHM3	1600	1700	0.5				



ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum average forward current	I <sub>F(AV)</sub>	$T_C$ = 105 °C, 180° conduction half sine wave	8			
Maximum peak one cycle	l	10 ms sine pulse, rated V <sub>RRM</sub> applied	125	Α		
non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, no voltage reapplied	150			
Maximum I <sup>2</sup> t for fusing	I <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s		
Waximum I-t for fusing	1-1	10 ms sine pulse, no voltage reapplied	110 A-S			
Maximum I <sup>2</sup> √t for fusing	I²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s		

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS
Maximum forward voltage drop	$V_{FM}$	8 A, T <sub>J</sub> = 25 °C		1.1	V
Forward slope resistance	r <sub>t</sub>	T 150 90		20	m $Ω$
Threshold voltage	V <sub>F(TO)</sub>	T <sub>J</sub> = 150 °C		0.82	V
Maximum reverse leakage current		T <sub>J</sub> = 25 °C	V <sub>R</sub> = Rated V <sub>RRM</sub>	0.05	mA
iviaximum reverse leakage current	I <sub>RM</sub>	T <sub>J</sub> = 150 °C	v <sub>R</sub> = nateu v <sub>RRM</sub>	0.50	IIIA

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-40 to +150	°C		
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W		
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA</sub> <sup>(1)</sup>		62	C/VV		
Approximate weight			1	g		
Approximate weight			0.03	oz.		
Marking device		Case style DPAK (TO-252AA)	8EWS	16SH		

#### Note

<sup>(1)</sup> When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W

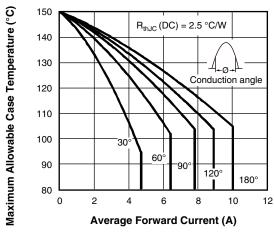


Fig. 1 - Current Rating Characteristics

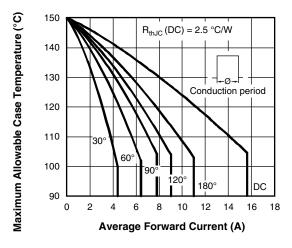


Fig. 2 - Current Rating Characteristics



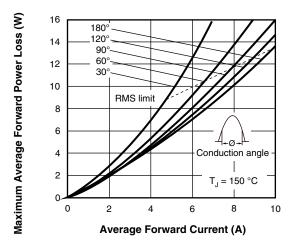


Fig. 3 - Forward Power Loss Characteristics

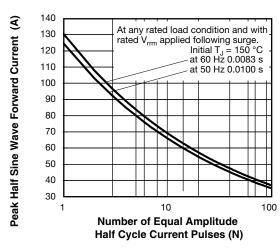


Fig. 5 - Maximum Non-Repetitive Surge Current

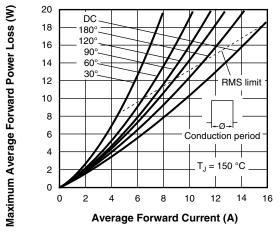


Fig. 4 - Forward Power Loss Characteristics

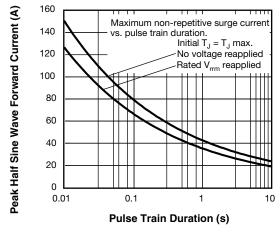


Fig. 6 - Maximum Non-Repetitive Surge Current

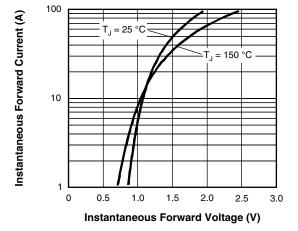


Fig. 7 - Forward Voltage Drop Characteristics

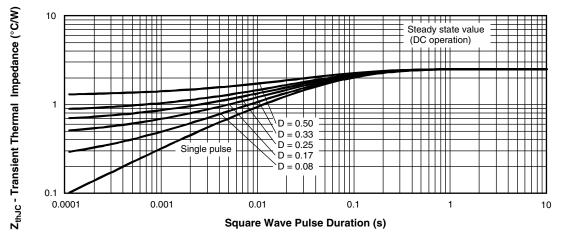


Fig. 8 - Thermal Impedance Z<sub>thJC</sub> Characteristics

### **ORDERING INFORMATION TABLE**

Device code	VS-	8	E	W	s	16	s	L	Н	M3
	1	2	3	4	5	6	7	8	9	10

1 - Vishay Semiconductors product

2 - Current rating (8 = 8 A)

Circuit configuration:

E = single

4 - Package:

W = DPAK (TO-252AA)

5 - Type of silicon:

S = standard recovery rectifier

6 - Voltage code x 100 = V<sub>RRM</sub> (16 = 1600 V)

7 - S = surface mountable

8 - L = tape and reel (left oriented), for different orientation contact factory

9 - H = AEC-Q101 qualified

10 - Environmental digit:

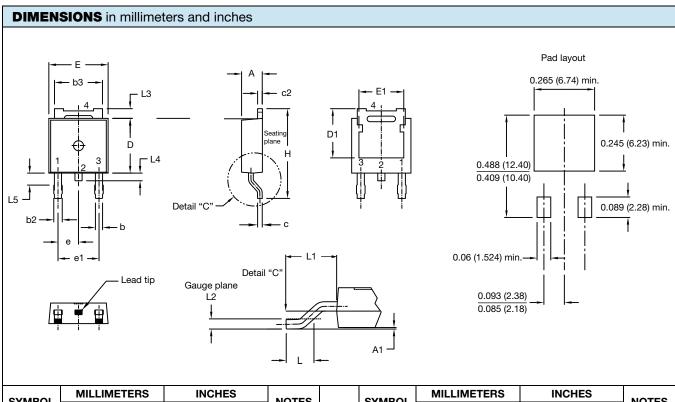
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-8EWS16SLHM3	3000	3000	13" diameter reel			

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95519</u>				
Part marking information	www.vishay.com/doc?95518			
Packaging information	www.vishay.com/doc?96495			
SPICE model	www.vishay.com/doc?96960			



## **DPAK (TO-252AA)**



SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	1	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	4.93	-	0.194	-	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIN	METERS INCHES			NOTES
OTMIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090	BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74	BSC	0.108	REF.	
L2	0.51	BSC	0.020	BSC	
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
	•	•		•	

#### **Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension



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